

HRG3000ORMII

High Rigid Grinder

Fully Automatic High Rigid Triple Axis Grinder
Less-damage Grinding with Shorter Process Time

————— **Low Cost** —————

————— **High Accuracy** —————

————— **Mirror Finish Surface Grinding** —————



Target Material

Si

Target Work

Size : $\phi 8$ to $\phi 12$ inch

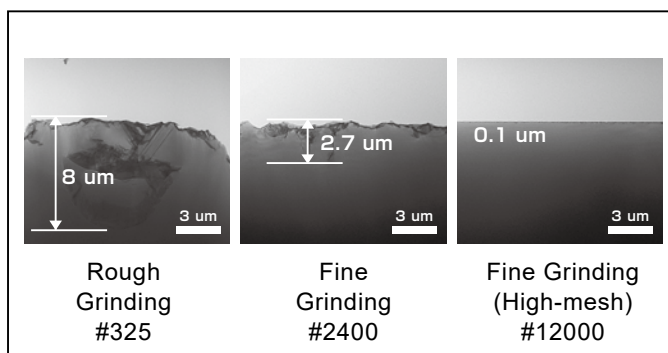
Throughput

Planning condition (UPH35)

Rough (#325, 10 $\mu\text{m}/\text{sec}$)	Process time 82 sec (658 μm)	Setup 20 sec
Semi-fine (#2400, 3 $\mu\text{m}/\text{sec}$)	82 sec (80 μm)	Setup 20 sec
Fine (#10000, 0.25 $\mu\text{m}/\text{sec}$)	82 sec (10 μm)	Setup 20 sec
Handling	85 sec	

UPH 3600/102=35.3

grinding Damage



Specification



No	Category	HRG3000X
		Full Automatic High Rigid Triple Axis Grinder Size: 1750 (W) x 3525 (D) x 1978 (H) mm Weight : 11000 kg
1	Appearance	
2	Maximum Wafer Size (mm)	300
3	Grinding Wheel Diameter (mm)	300
4	Grinding Wheel Rotation (rpm)	3600
5	Work Spindle Axis Rotation (rpm)	650
6	Grinding Wheel Spindle Power (kw)	11
7	Total Thickness Variation : TTV (μm)	0.5 (with Auto TTV)
8	Wafer to Wafer Thickness Variation : WTW (μm)	± 0.5 (with Auto TTV)



No	Category	RM3000HRG
		Size: 1450 (W) x 4250 (D) x 1800 (H) mm Weight : 2720 kg
1	Appearance	
2	Maximum Wafer Size (mm)	300
3	Maximum Dicing Tape Diameter (mm)	$\phi 210$ (Roll width 400 mm)
4	Maximum Peeling Tape Diameter (mm)	$\phi 200$ (Roll width 50 mm)
5	Wafer Mounting Accuracy	X and Y direction : ± 0.5 mm θ direction : $\pm 0.5^\circ$

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Contact
information

